

#### ICS8705 NRND

#### NOT RECOMMENDED FOR NEW DESIGNS

#### GENERAL DESCRIPTION

The ICS8705 is a highly versatile 1:8 Differential-to-LVCMOS/ LVTTL Clock Generator. The ICS8705 has two selectable clock inputs. The CLK1, nCLK1 pair can accept most standard differential input levels. The single ended CLK0 input accepts LVCMOS or LVTTL input levels. The ICS8705 has a fully integrated PLL and can be configured as zero delay buffer, multiplier or divider and has an input and output frequency range of 15.625MHz to 250MHz. The reference divider, feedback divider and output divider are each programmable, thereby allowing for the following output-to-input frequency ratios: 8:1, 4:1, 2:1, 1:1, 1:2, 1:4, 1:8. The external feedback allows the device to achieve "zero delay" between the input clock and the output clocks. The PLL\_SEL pin can be used to bypass the PLL for system test and debug purposes. In bypass mode, the reference clock is routed around the PLL and into the internal output dividers.

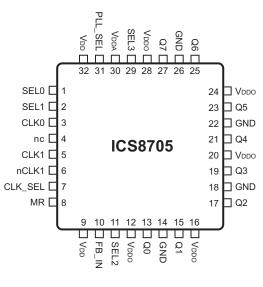
#### **F**EATURES

- 8 LVCMOS/LVTTL outputs,  $7\Omega$  typical output impedance
- Selectable CLK1, nCLK1 or LVCMOS/LVTTL clock inputs
- CLK1, nCLK1 pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL
- · CLK0 input accepts LVCMOS or LVTTL input levels
- Output frequency range: 15.625MHz to 250MHz
- Input frequency range: 15.625MHz to 250MHz
- VCO range: 250MHz to 500MHz
- External feedback for "zero delay" clock regeneration with configurable frequencies
- Programmable dividers allow for the following output-toinput frequency ratios: 8:1, 4:1, 2:1, 1:1, 1:2, 1:4, 1:8
- · Fully integrated PLL
- Cycle-to-cycle jitter: 45ps (maximum)
- Output skew: CLK0, 65ps (maximum)
   CLK1, nCLK1, 55ps (maximum)
- Static Phase Offset: 25 ±125ps (maximum), CLK0
- Full 3.3V or 2.5V operating supply
- 0°C to 70°C ambient operating temperature
- · Lead-Free package fully RoHS compliant
- Not Recommended for New Designs.
   For new designs, contact IDT.

#### **BLOCK DIAGRAM**

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#### PIN ASSIGNMENT



#### 32-Lead LQFP

7mm x 7mm x 1.4 mm Y Package Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Т	уре	Description
1, 2, 11	SEL0, SEL1, SEL2	Input	Pulldown	Determines output divider values in Table 3. LVCMOS/LVTTL interface levels.
3	CLK0	Input	Pulldown	Clock input. LVCMOS/LVTTL interface levels.
4	nc			No connect.
5	CLK1	Input	Pulldown	Non-inverting differential clock input.
6	nCLK1	Input	Pullup	Inverting differential clock input.
7	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects differential CLK1, nCLK1. When LOW, selects LVCMOS CLK0. LVCMOS/LVTTL interface levels.
8	MR	Input	Pulldown	Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the outputs to go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS/LVTTL interface levels.
9, 32	V <sub>DD</sub>	Power		Core supply pins.
10	FB_IN	Input	Pulldown	LVCMOS/LVTTL feedback input to phase detector for regenerating clocks with "zero delay". Connect to one of the outputs. LVCMOS/LVTTL interface levels.
12, 16, 20, 24, 28	V <sub>DDO</sub>	Power		Output supply pins.
13, 15, 17, 19, 21, 23, 25, 27	Q0, Q1, Q2, Q3, Q4, Q5, Q6, Q7	Output		Clock output. $7\Omega$ typical output impedance. LVCMOS/LVTTL interface levels.
14, 18, 22, 26	GND	Power		Power supply ground.
29	SEL3	Input	Pulldown	Determines output divider values in Table 3. LVCMOS/LVTTL interface levels.
30	$V_{\scriptscriptstyle DDA}$	Power		Analog supply pin.
31	PLL_SEL	Input	Pullup	Selects between the PLL and reference clock as input to the dividers. When LOW, selects the reference clock (PLL Bypass). When HIGH, selects PLL (PLL Enabled). LVCMOS/LVTTL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		ΚΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		ΚΩ
C <sub>PD</sub>	Power Dissipation Capacitance (per output)	$V_{DD}$ , $V_{DDO}$ , $V_{DDA} = 3.465V$		23		pF
R <sub>out</sub>	Output Impedance			7		Ω



TABLE 3A. PLL ENABLE FUNCTION TABLE

			Inputs		Outputs PLL_SEL = 1 PLL Enable Mode
SEL3	SEL2	SEL1	SEL0	Reference Frequency Range (MHz)	Q0:Q7
0	0	0	0	125 - 250	÷ 1
0	0	0	1	62.5 - 125	÷ 1
0	0	1	0	31.25 - 62.5	÷ 1
0	0	1	1	15.625 -31.25	÷ 1
0	1	0	0	125 - 250	÷ 2
0	1	0	1	62.5 - 125	÷ 2
0	1	1	0	31.25 - 62.5	÷ 2
0	1	1	1	125 - 250	÷ 4
1	0	0	0	62.5 - 125	÷ 4
1	0	0	1	125 - 250	÷ 8
1	0	1	0	62.5 - 125	x 2
1	0	1	1	31.25 - 62.5	x 2
1	1	0	0	15.625 - 31.25	x 2
1	1	0	1	31.25 - 62.5	x 4
1	1	1	0	15.625 - 31.25	x 4
1	1	1	1	15.625 - 31.25	x 8

TABLE 3B. PLL BYPASS FUNCTION TABLE

	Inp	outs		Outputs PLL_SEL = 0 PLL Bypass Mode
SEL3	SEL2	SEL1	SEL0	Q0:Q7
0	0	0	0	÷ 8
0	0	0	1	÷ 8
0	0	1	0	÷ 8
0	0	1	1	÷ 16
0	1	0	0	÷ 16
0	1	0	1	÷ 16
0	1	1	0	÷ 32
0	1	1	1	÷ 32
1	0	0	0	÷ 64
1	0	0	1	÷ 128
1	0	1	0	÷ 4
1	0	1	1	÷ 4
1	1	0	0	÷ 8
1	1	0	1	÷ 2
1	1	1	0	÷ 4
1	1	1	1	÷ 2





#### ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V<sub>DD</sub>

-0.5V to  $V_{DD} + 0.5 V$ Inputs, V<sub>1</sub>

-0.5V to  $V_{DDO} + 0.5V$ Outputs, V<sub>O</sub>

Package Thermal Impedance,  $\theta_{IA}$ 47.9°C/W (0 lfpm)

Storage Temperature,  $T_{STG}$ -65°C to 150°C NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the DC Characteristics or AC Characteristics is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 3.3V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>DD</sub>	Core Supply Voltage		3.135	3.3	3.465	٧
V <sub>DDA</sub>	Analog Supply Voltage		3.135	3.3	3.465	٧
V <sub>DDO</sub>	Output Supply Voltage		3.135	3.3	3.465	V
I <sub>DD</sub>	Power Supply Current				96	mA
I <sub>DDA</sub>	Analog Supply Current				15	mA
I <sub>DDO</sub>	Output Supply Current				20	mA

Table 4B. LVCMOS / LVTTL DC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 3.3V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	PLL_SEL, CLK_SEL, SEL0, SEL1, SEL2, SEL3, FB_IN, MR		2		V <sub>DD</sub> + 0.3	V
		CLK0		2		$V_{DD} + 0.3$	V
V <sub>IL</sub>	Input Low Voltage	PLL_SEL, CLK_SEL, SEL0, SEL1, SEL2, SEL3, FB_IN, MR		-0.3		0.8	V
		CLK0		-0.3		V <sub>DD</sub> + 0.3  V <sub>DD</sub> + 0.3  0.8  1.3  150  5	V
I <sub>IH</sub>	Input High Current	CLK0, CLK_SEL MR, FB_IN, SEL0, SEL1, SEL2, SEL3	$V_{DD} = V_{IN} = 3.465V$			150	μΑ
		PLL_SEL	$V_{DD} = V_{IN} = 3.465V$			5	μΑ
I <sub>IL</sub>	Input Low Current	CLK0, CLK_SEL MR, FB_IN, SEL0, SEL1, SEL2, SEL3	V <sub>DD</sub> = 3.465V, V <sub>IN</sub> = 0V	-5			μΑ
		PLL_SEL	$V_{DD} = 3.465V, V_{IN} = 0V$	-150			μΑ
V <sub>OH</sub>	Output High Voltage; NOTE 1			2.6			V
V <sub>OL</sub>	Output Low Vo	oltage; NOTE 1				0.5	٧

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DDO}/2$ . In the Parameter Measurement Information Section, see "3.3V Output Load Test Circuit".



Table 4C. Differential DC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 3.3V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Innut Ligh Current	CLK1	$V_{DD} = V_{IN} = 3.465V$			150	μΑ
'ін	Input High Current	nCLK1	$V_{DD} = V_{IN} = 3.465V$	$I_{IN} = 3.465V$ 150 $I_{IN} = 3.465V$ 5 $I_{IN} = 3.465V$ 5 $I_{IN} = 3.465V$ 5 $I_{IN} = 3.465V$ 150 $I_{IN} = 3.465V$ 150 $I_{$	5	μΑ	
	Innut Low Current	CLK1	$V_{DD} = 3.465V, V_{IN} = 0V$	-5			μΑ
I <sub>IL</sub>	Input Low Current	nCLK1	$V_{DD} = 3.465V, V_{IN} = 0V$	-150		5	μΑ
V <sub>PP</sub>	Peak-to-Peak Input	Voltage		0.15		1.3	V
V <sub>CMR</sub>	Common Mode Inp NOTE 1, 2	ut Voltage;		GND + 0.5		V <sub>DD</sub> - 0.85	V

NOTE 1: Common mode voltage is defined as  $V_{_{\mbox{\scriptsize IH}}}$ .

NOTE 2: For single ended applications, the maximum input voltage for CLK1, nCLK1 is V<sub>nn</sub> + 0.3V.

Table 5A. AC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 3.3V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency			15.625		250	MHz
to	Propagation Delay,	CLK0	$PLL\_SEL = 0V,$ $f \le 250MHz, Qx \div 2$	5		7	ns
ιρ <sub>LH</sub>	Low-to-High; NOTE 1	CLK1, nCLK1	PLL_SEL = 0V, $f \le 250MHz$ , Qx ÷ 2	5		250	ns
		CLK0	PLL_SEL = $3.3V$ , fREF $\leq 200MHz$ , Qx $\div 1$	-100	250 7 7.3 25 150 + 135 285 +100 250 -25 100 150 300 65 55 45 1 950 57	ps	
t(Ø)	Static Phase Offset; NOTE 2, 4	CLK1 pCLK1	PLL_SEL = 3.3V, $fREF \le 167MHz$ , $Qx \div 1$	-15	+ 135	285	ps
		CLK1, HCLK1	PLL_SEL = $3.3V$ , fREF = $200MHz$ , Qx $\div 1$	-50	+100	250	ps
		agation Delay, o-High; NOTE 1	100	ps			
		CLK1, nCLK1		0	150	250 7 7.3 150 285 250 100 300 65 55 45 1 950 57	ps
tok(o)	Output Skew;	CLK0	PLL_SEL = 0V			65	ps
isk(0)	NOTE 3, 4	CLK1, nCLK1	PLL_SEL = 0V			250 7 7.3 150 285 250 100 300 65 55 45 1 950 57	ps
tjit(cc)	Cycle-to-Cycle Jitter; N	OTE 4	f <sub>OUT</sub> > 40MHz			45	ps
t_	PLL Lock Time					1	mS
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time			400		950	ps
$t(\emptyset)$				43		57	%
	Output Duty Cycle		PLL x 4 mode, fin = 45MHz, fOUT = 180MHz	47		53	%

All parameters measured at  $f_{MAX}$  unless noted otherwise. NOTE 1: Measured from the differential input crossing point to the output at  $V_{DDO}/2$ .

NOTE 2: Defined as the time difference between the input reference clock and the average feedback input signal when the PLL is locked and the input reference frequency is stable.

NOTE 3: Defined as skew between outputs at the same supply voltages and with equal load conditions.

Measured at V<sub>DDO</sub>/2.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



Table 4D. Power Supply DC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 2.5 V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>DD</sub>	Core Supply Voltage		2.375	2.5	2.625	V
V <sub>DDA</sub>	Analog Supply Voltage		2.375	2.5	2.625	V
V <sub>DDO</sub>	Output Supply Voltage		2.375	2.5	2.625	V
I <sub>DD</sub>	Power Supply Current				90	mA
I <sub>DDA</sub>	Analog Supply Current				15	mA
I <sub>DDO</sub>	Output Supply Current				20	mA

Table 4E. LVCMOS / LVTTL DC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 2.5V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	PLL_SEL, CLK_SEL, SEL0, SEL1, SEL2, SEL3, FB_IN, MR		2		V <sub>DD</sub> + 0.3	V
		CLK0		2			V
V <sub>IL</sub>	Input Low Voltage	PLL_SEL, CLK_SEL, SEL0, SEL1, SEL2, SEL3, FB_IN, MR		-0.3		0.8	V
		CLK0		-0.3		1.3	V
I <sub>IH</sub>	Input High Current	CLK0, CLK_SEL MR, FB_IN, SEL0, SEL1, SEL2, SEL3	$V_{DD} = V_{IN} = 2.625V$			150	μΑ
		PLL_SEL	$V_{DD} = V_{IN} = 2.625V$			V <sub>DD</sub> + 0.3 V <sub>DD</sub> + 0.3 0.8 1.3 150 5	μΑ
I <sub>IL</sub>	Input Low Current	CLK0, CLK_SEL MR, FB_IN, SEL0, SEL1, SEL2, SEL3	$V_{DD} = 2.625V, V_{IN} = 0V$	-5			μΑ
		PLL_SEL	$V_{DD} = 2.625V, V_{IN} = 0V$	-150		V <sub>DD</sub> + 0.3 V <sub>DD</sub> + 0.3 0.8 1.3 150 5	μΑ
V <sub>OH</sub>	Output High Voltage; NOTE 1			1.8			V
V <sub>OL</sub>	Output Low Vo	oltage; NOTE 1				0.5	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DDO}/2$ . In the Parameter Measurement Information section, see "2.5V Output Load Test Circuit" figure.

Table 4F. Differential DC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 2.5V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	CLK1	$V_{DD} = V_{IN} = 2.625V$			150	μΑ
I'IH	Input High Current	nCLK1	$V_{DD} = V_{IN} = 2.625V$	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	μΑ		
	Input Low Current	CLK1	$V_{DD} = 2.625V, V_{IN} = 0V$	-5			μΑ
' <sub>IL</sub>	Imput Low Current	nCLK1	$V_{DD} = 2.625V, V_{IN} = 0V$	-150		150 5 1.3	μΑ
V <sub>PP</sub>	Peak-to-Peak Input Voltage			0.15		1.3	V
V <sub>CMR</sub>	Common Mode Inpu NOTE 1, 2	t Voltage;		GND + 0.5		V <sub>DD</sub> - 0.85	V

NOTE 1: Common mode voltage is defined as  $V_{\text{IH}}$ . NOTE 2: For single ended applications, the maximum input voltage for CLK1, nCLK1 is  $V_{\text{DD}}$  + 0.3V.



Table 5B. AC Characteristics,  $V_{DD} = V_{DDA} = V_{DDO} = 2.5V \pm 5\%$ , TA = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency			15.625		250	MHz
	Propagation Delay,	CLK0	$\begin{aligned} \text{PLL\_SEL} &= \text{0V}, \\ \text{f} &\leq 250 \text{MHz},  \text{Qx} \div 2 \end{aligned}$	5		7	ns
tp <sub>LH</sub>	Low-to-High; NOTE 1	CLK1, nCLK1	PLL_SEL = 0V, $f \le 250MHz$ , Qx ÷ 2	5		250	ns
		CLK0	PLL_SEL = 2.5V, fREF $\leq$ 200MHz, Qx $\div$ 1	-250	25	250 7 7.3 200 250 300 100 300 65 55 45 ±50 1 950 57	ps
tck(o)	Static Phase Offset; NOTE 2, 4	CLK1, nCLK1	PLL_SEL = 2.5V, $fREF = 133MHz, Qx \div 1$	-50	100	250	ps
		CLK1, HCLK1	PLL_SEL = 2.5V, $fREF = 200MHz, Qx \div 1$	-100	0 +100	300	ps
		CLK0	PLL_SEL = 2.5V, fREF = 66MHz, Qx * 2	-150	-25	100	ps
		CLK1, nCLK1	PLL_SEL = 2.5V, fREF = 66MHz, Qx * 2	0	150	250 7 7.3 200 250 300 100 300 65 55 45 ±50 1 950 57	ps
tol(a)	Output Skew;	CLK0	PLL_SEL = 0V			65	ps
isk(0)	NOTE 3, 4	CLK1, nCLK1	PLL_SEL = 0V			250 7 7.3 200 250 300 100 300 65 55 45 ±50 1 950 57	ps
tjit(cc)	Cycle-to-Cycle Jitter; N	OTE 4	f <sub>OUT</sub> > 40MHz			45	ps
tjit(θ)	Phase Jitter; NOTE 4,	5	PLL_SEL = 2.5V, fREF = 66MHz, Qx * 2			±50	ps
t,	PLL Lock Time					1	mS
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time			400		950	ps
				43		57	%
odc	Output Duty Cycle		PLL x 4 mode, fin = 45MHz, fOUT = 180MHz	45		55	%

All parameters measured at f<sub>MAX</sub> unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output at V<sub>DDO</sub>/2.

NOTE 2: Defined as the time difference between the input reference clock and the average feedback input signal when the PLL is locked and the input reference frequency is stable.

NOTE 3: Defined as skew between outputs at the same supply voltages and with equal load conditions.

Measured at V<sub>DDO</sub>/2.

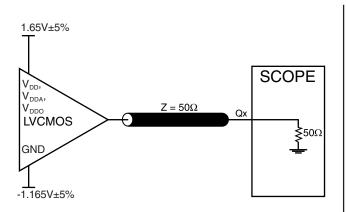
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

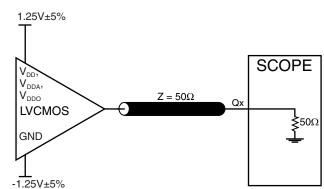
NOTE 5: Phase jitter is dependent on the input source used.





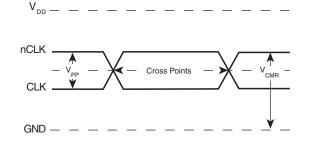
#### PARAMETER MEASUREMENT INFORMATION

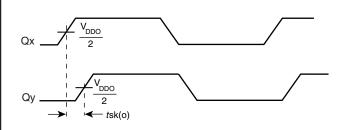




#### 3.3V Core/3.3V OUTPUT LOAD AC TEST CIRCUIT

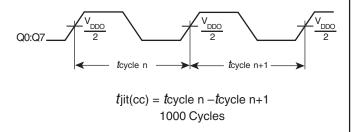
#### 2.5V CORE/2.5V OUTPUT LOAD ACTEST CIRCUIT

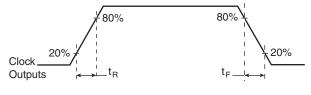




#### DIFFERENTIAL INPUT LEVEL

#### **OUTPUT SKEW**



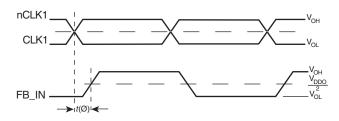


#### CYCLE-TO-CYCLE JITTER

#### OUTPUT RISE/FALL TIME

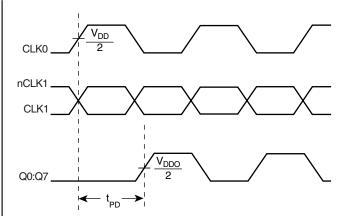






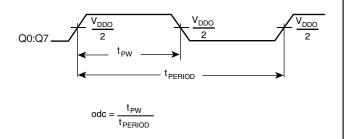
$$t$$
jit( $\emptyset$ ) =  $t(\emptyset)$  —  $t(\emptyset)$  mean = Phase Jitter  $t(\emptyset)$  mean = Static Phase Offset

(where  $t(\mathcal{O})$  is any random sample, and  $t(\mathcal{O})$  mean is the average of the sampled cycles measured on controlled edges)



#### PHASE JITTER & STATIC PHASE OFFSET

#### PROPAGATION DELAY



#### **OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD**



#### **APPLICATION INFORMATION**

#### Power Supply Filtering Techniques

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS8705 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL.  $V_{\rm DD}, V_{\rm DDA},$  and  $V_{\rm DDO}$  should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. Figure 1 illustrates how a  $10\Omega$  resistor along with a  $10\mu F$  and a  $.01\mu F$  bypass capacitor should be connected to each  $V_{\rm DDA}$ .

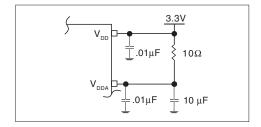
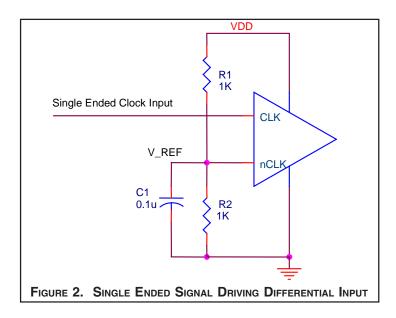


FIGURE 1. POWER SUPPLY FILTERING

#### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{CC}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{\rm cc}$  = 3.3V, V\_REF should be 1.25V and R2/R1 = 0.609.





#### DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both  $\rm V_{SWING}$  and  $\rm V_{OH}$  must meet the  $\rm V_{PP}$  and  $\rm V_{CMR}$  input requirements. Figures 3A to 3D show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are

examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in Figure 4A, the input termination applies for LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

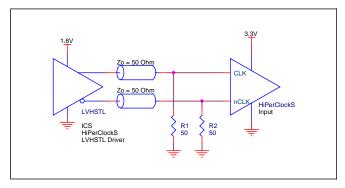


FIGURE 3A. **CLK/NCLK INPUT DRIVEN BY** LVHSTL DRIVER

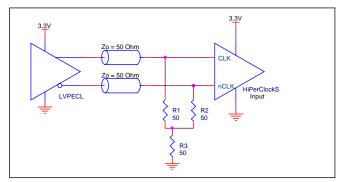


FIGURE 3B. CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

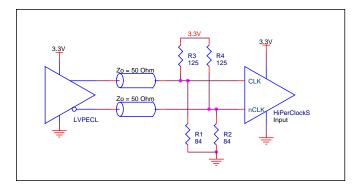


FIGURE 3C. CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

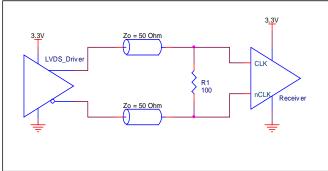


FIGURE 3D. CLK/NCLK INPUT DRIVEN BY 3.3V LVDS DRIVER





#### LAYOUT GUIDELINE

The schematic of the ICS8705 layout example is shown in Figure 4A. The ICS8705 recommended PCB board layout for this example is shown in Figure 4B. This layout example is used as a general guideline. The layout in the actual system will

depend on the selected component types, the density of the components, the density of the traces, and the stack up of the P.C. board.

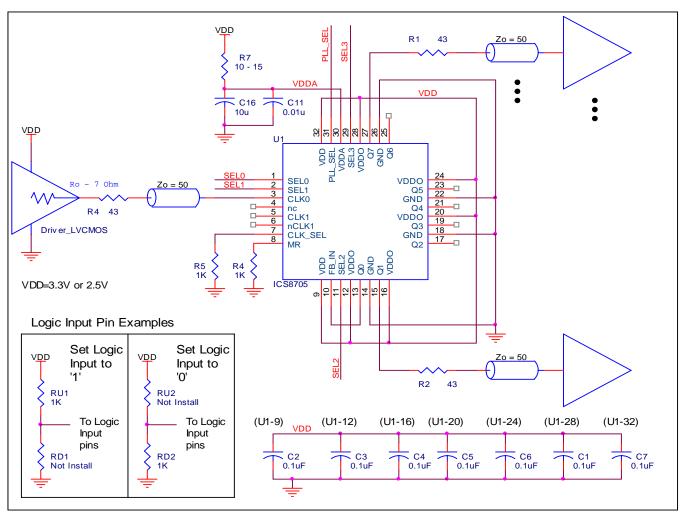


FIGURE 4A. ICS8705 LVCMOS CLOCK GENERATOR SCHEMATIC EXAMPLE





The following component footprints are used in this layout example:

All the resistors and capacitors are size 0603.

#### POWER AND GROUNDING

Place the decoupling capacitors as close as possible to the power pins. If space allows, placement of the decoupling capacitor on the component side is preferred. This can reduce unwanted inductance between the decoupling capacitor and the power pin caused by the via.

Maximize the power and ground pad sizes and number of vias capacitors. This can reduce the inductance between the power and ground planes and the component power and ground pins.

The RC filter consisting of R7, C11, and C16 should be placed as close to the  $\rm V_{\rm DDA}$  pin as possible.

#### **CLOCK TRACES AND TERMINATION**

Poor signal integrity can degrade the system performance or cause system failure. In synchronous high-speed digital systems, the clock signal is less tolerant to poor signal integrity than other signals. Any ringing on the rising or falling edge or excessive ring back can cause system failure. The shape of the trace and the

trace delay might be restricted by the available space on the board and the component location. While routing the traces, the clock signal traces should be routed first and should be locked prior to routing other signal traces.

- The differential  $50\Omega$  output traces should have same length.
- Avoid sharp angles on the clock trace. Sharp angle turns cause the characteristic impedance to change on the transmission lines.
- Keep the clock traces on the same layer. Whenever possible, avoid placing vias on the clock traces. Placement of vias on the traces can affect the trace characteristic impedance and hence degrade signal integrity.
- To prevent cross talk, avoid routing other signal traces in parallel with the clock traces. If running parallel traces is unavoidable, allow a separation of at least three trace widths between the differential clock trace and the other signal trace.
- Make sure no other signal traces are routed between the clock trace pair.
- The series termination resistors should be located as close to the driver pins as possible.

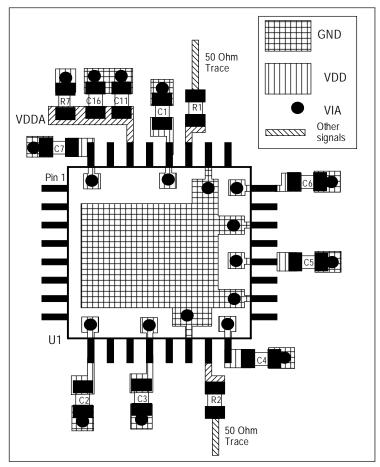


FIGURE 4B. PCB BOARD LAYOUT FOR ICS8705





### RELIABILITY INFORMATION

#### Table 6. $\theta_{\text{JA}} \text{vs. Air Flow Table for 32 Lead LQFP}$

#### $\theta_{JA}$ by Velocity (Linear Feet per Minute)

200 500 Single-Layer PCB, JEDEC Standard Test Boards 67.8°C/W 55.9°C/W 50.1°C/W Multi-Layer PCB, JEDEC Standard Test Boards 47.9°C/W 42.1°C/W 39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### TRANSISTOR COUNT

The transistor count for ICS8705 is: 3126



#### PACKAGE OUTLINE - Y SUFFIX FOR 32 LEAD LQFP

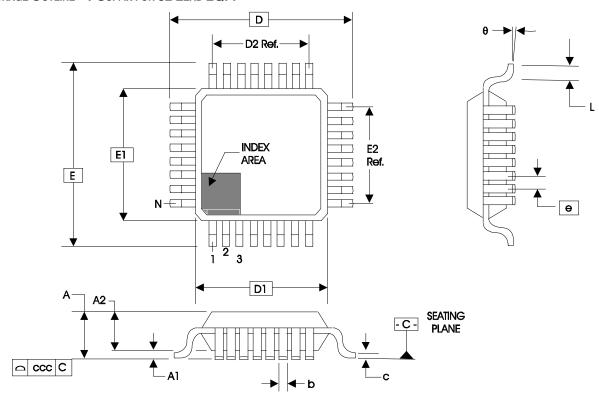


TABLE 7. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS						
OVMDOL	BBA					
SYMBOL	MINIMUM	NOMINAL	MAXIMUM			
N	32					
Α			1.60			
A1	0.05		0.15			
A2	1.35	1.40	1.45			
b	0.30	0.37	0.45			
С	0.09		0.20			
D	9.00 BASIC					
D1	7.00 BASIC					
D2	5.60 Ref.					
E	9.00 BASIC					
E1	7.00 BASIC					
E2	5.60 Ref.					
е	0.80 BASIC					
L	0.45	0.60	0.75			
θ	0°		7°			
ccc			0.10			

Reference Document: JEDEC Publication 95, MS-026



#### TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
8705BYLF	ICS8705BYLF	32 lead "Lead Free" LQFP	Tray	0°C to +70°C
8705BYLFT	ICS8705BYLF	32 lead "Lead Free" LQFP	2500 Tape and Reel	0°C to +70°C

NOTE: "LF" suffix to the part number are the PB-free configuration, RoHS compliant

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	REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change	Date		
Α		1	Updated Block Diagram	1/25/02		
	T3A		PLL Enable Function Table - revised the Reference Frequency Range column			
В	T5A	5	3.3V AC Characteristics Table - updated the Output Frequency row from 350MHz Max. to 275MHz Max.	3/14/02		
	T4D:T4F; T5B	6, 7	Added 2.5V tables.			
	T3A	3	PLL Enable Function Table - revised the Reference Frequency Range column			
С	T5A	5	3.3V AC Characteristics Table - updated the Output Frequency row from 275MHz Max. to 250MHz Max.	4/4/02		
	T5B	7	2.5V AC Characteristics Table - updated the Output Frequency row from 275MHz Max. to 250MHz Max.			
С	T1	2	Pin Description Table - revised power pin descriptions.	4/10/02		
С	T2	2	Pin Characteristics Table - add 23pF (typical) in C <sub>PD</sub> row.	7/15/02		
С	T1	2	Pin Description Table - Pin# 10 from description, replaced "Connect to pin 10." with "Connect to one of the outputs."	8/1/02		
С	C T1	2	Revised CLK0 description and MR description.	8/21/02		
		8	Revised Output Rise/Fall Time Diagram.	0/21/02		
	T1, T4A, T4D	2, 4, 6	Revised description for $V_{DD}$ to read Core supply from Positive supply.			
D	T5A, T5B	5, 7	AC Characteristics, added another row to "odc" with different test conditions and values.	11/22/02		
			Updated format.			
Е	1	2	Pin Description table - revised MR description.	1/22/03		
	T5A & T5B	5 & 7	AC tables - Changed the Static Phase Offset limits for CLK1, nCLK1.			
F	T5A & T5B	5 & 7	AC tables - added Static Phase Offset with "fREF = 66MHz, Qx * 2".  3.3V AC table - corrected typo in SPO parameter to read NOTE 4 from NOTE 7.			
			Throughout datasheet revised title to read "Differential-to-LVCMOS/LVTTL"			
G T5B	T5B	7	2.5V AC Characteristics Table - added Phase Jitter spec, and Note 5.	3/14/03		
		9	Replaced Static Phase Offset Diagram with Phase Jitter & SPO Diagram.			
G T	T2	2	Pin Characteristics Table - changed C <sub>IN</sub> from 4pF max. to 4pF typical.	5/15/03		
		11	Added Differential Clock Input Interface section.	3/13/03		
G		12 & 13	Added Layout Guideline	6/6/03		
G	Т6	14	Ordering Information Table - added "Lead-Free" part number	6/16/04		
G		1	Features Section - added temperature bullet.	3/18/05		
G	Т8	16	Ordering Information Table - Added "Lead-Free" note.	3/10/03		
Н	Т8	16 18	Updated datasheet's header/footer with IDT from ICS. Removed "ICS" prefix from Part/Order Number column. Corrected packaging column. Added Contact Page.			
Н		1	NRND - Not Recommended For New Designs	5/21/13		
	l	Ι ΄	1	1 5/21/15		



ICS8705 NRND

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